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(57)ABSTRACT

An object of the present disclosure is to be able to further reduce the size of a substrate structure including a plurality of elements. The substrate structure includes: a base substrate that includes a first conductive plate and a second conductive plate; a first element connected to the first conductive plate and the second conductive plate; and a second element connected to the first conductive plate and the second conductive plate. The first conductive plate and the second conductive plate are disposed on the same plane on the base substrate in a state of being electrically insulated from each other, the first element is mounted on a first main surface of the base substrate, and the second element is mounted on a second main surface that is on the opposite side to the first main surface relative to the base substrate.

